

L Number	Hits	Search Text	DB	Time stamp
1	2621640	chip dice semiconductor ic die (integrated adj circuit) microchipmcm csp mems opticelectronic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:23
2	3674283	substrate carrier cb pcb board (printed adj4 board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:24
3	703686	flipchip (flip adj chip) bump ball bga	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:25
4	1957976	(non adj (thermoset thermosetting)) thermoplastic polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:26
5	125316	((non adj (thermoset thermosetting)) thermoplastic polymer) with (adhesive adhesion sphere)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:27
6	1920	(flipchip (flip adj chip) bump ball bga) same (((non adj (thermoset thermosetting)) thermoplastic polymer) with (adhesive adhesion sphere))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:28
7	1002	((flipchip (flip adj chip) bump ball bga) same (((non adj (thermoset thermosetting)) thermoplastic polymer) with (adhesive adhesion sphere))) and (chip dice semiconductor ic die (integrated adj circuit) microchipmcm csp mems opticelectronic) and (substrate carrier cb pcb board (printed adj4 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:29
8	560	(remove removal removable) and (((flipchip (flip adj chip) bump ball bga) same (((non adj (thermoset thermosetting)) thermoplastic polymer) with (adhesive adhesion sphere))) and (chip dice semiconductor ic die (integrated adj circuit) microchipmcm csp mems opticelectronic) and (substrate carrier cb pcb board (printed adj4 board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/10/03 20:29